



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
E-L6258EP	D5EH*U708FB6	A	MU1A	2016-01-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	480.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	10.30,7.5,2.28	37	gull wing	
Comment	Package: PowerSSO36			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : REACH-17th December 2015

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	D5EH*U708FB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	18.660	mg	supplier	die	Silicon (Si)	7440-21-3		17.979	mg	963505	37456
				supplier	metallization	Aluminium (Al)	7429-90-5		0.103	mg	5520	215
				supplier	metallization	Copper (Cu)	7440-50-8		0.002	mg	107	4
				supplier	Passivation	Silicon Nitride	12033-89-5		0.058	mg	3108	121
				supplier	Passivation	Silicon Oxide	7631-86-9		0.242	mg	12969	504
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.010	mg	536	21
				supplier	back side metallization	Gold (Au)	7440-57-5		0.027	mg	1447	56
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.092	mg	4930	192
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.147	mg	7878	306
				Leadframe	Copper & Its alloys	127.268	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						2.873	mg	22574	5985
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.173	mg	1359	360
supplier	alloy	Zinc (Zn)	7440-66-6						0.150	mg	1179	313
supplier	metallization	Silver (Ag)	7440-22-4						1.912	mg	15023	3983
Soft solder	Other inorganic materials	11.605	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	11.315	mg	975011	23573
				supplier	solder	Silver (Ag)	7440-22-4		0.174	mg	14994	363
				supplier	solder	Tin (Sn)	7440-31-5		0.116	mg	9996	242
Bonding wires	Other inorganic materials	2.850	mg	supplier	wire	Gold (Au)	7440-57-5		2.850	mg	1000000	5938
Encapsulation	Other Organic Materials	315.384	mg	supplier	mold compound	silica vitreous	60676-86-0		279.116	mg	885004	581492
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		16.715	mg	52999	34823
				supplier	mold compound	Phenol Resin	205830-20-2		12.615	mg	39999	26281
				supplier	mold compound	epoxy resin	25068-38-6		6.308	mg	20001	13142
Connections coating	Solder	4.233	mg	supplier	mold compound	carbon black	1333-86-4		0.630	mg	1998	1313
				supplier	solder alloy	Tin (Sn)	7440-31-5		4.233	mg	1000000	8819